

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("5917601").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/03 15:31
L2	1050	wafer near3 position near3 edge	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:32
L3	21	2 and array with position with sens\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:43
L4	1131	wafer with displacement with position	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:40
L5	60	2 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:40
L6	416	wafer with displacement with measuring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:40
L7	6	2 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:41
L8	198	laser adj distance adj sens\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:41
L9	18	8 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 15:46

L10	1	("5886521").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/03 16:30
L11	1	("4819167").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/03 16:30
L12	1	"4449885".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:30
L13	1	"4507078".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:31
L14	1	"4523985".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:31
L15	1	"4647266".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:31
L16	1	"4705951".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:31
L17	1	"4720635".PN.	USPAT; USOCR	OR	ON	2005/08/03 16:32
L18	107580	(wafer or substrate) near2 position\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:43
L19	7055	(wafer or substrate) near2 position\$4.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:58
L20	23	19 and array with sens\$4 with position	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:58
L21	182	(wafer or substrate) near2 position\$4 near4 measur\$4.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:50
L22	1	21 and array with sens\$4 with position	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:51

L23	2494	wafer near4 thickness near4 measur\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 16:58
L24	127	23 and (wafer or substrate) near2 position\$4 near3 measur\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:07
L25	6	24 and eddy adj current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:10
L26	331	324/230.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:37
L27	116	26 and (wafer or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:11
L28	7	27 and array near4 sens\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:16
L29	147	23 and determin\$4 near2 position	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:17
L30	7	29 and eddy adj current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:17

L31	441	324/229.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:37
L32	88	26 and gap	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 17:37